

ABSTRACT

The invention relates to a process and a device for the manufacture of a primary unit pack of a wafer, wherein a laminate made up of a carrier sheet and an active substance film is cross-cut at a predetermined length and is detached from the carrier sheet and guided between two packaging material webs and, along with said packaging material webs, is conveyed to a sealing station, the packaging material webs are sealed to form a bag and said bag is separated from the packaging material webs. The invention solves the task of configuring the process and the device in such a manner that the wafer material is not subjected to mechanical stress. The process provides for the carrier sheet (2), which has been detached from the active substance film (3), to be pulled forward over the predetermined length of the wafer (21), and the active substance film (3), which has been detached from said carrier sheet (2), is simultaneously guided, without being subjected to mechanical stress, with its front end between the packaging material webs (12), which are in a resting condition, and is received and fixed by said packaging material webs (12) and transversely cut at a distance therefrom so as to form a wafer (21) of the predetermined length, and that subsequently the wafer (21) is pulled forward together with and synchronously with the packaging material webs (12) and conveyed to the sealing station (17/18). To this end, the device is provided with a device (11) for feeding and pulling the packaging material comprising a receiving and clamping device (13/14) for the front end of the active substance film (3) and arranged in vertical direction below the separating roll (7) and the crosscutting tool (10).

(Fig. 1)